

Beginning from a silicon wafer



Side View



Top View

Thermal Oxidation



Side View

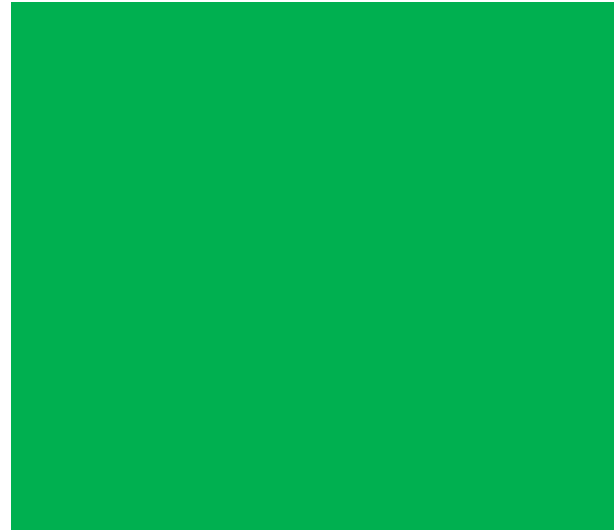


Top View

Spin-on Photo Resist (PR)



Side View

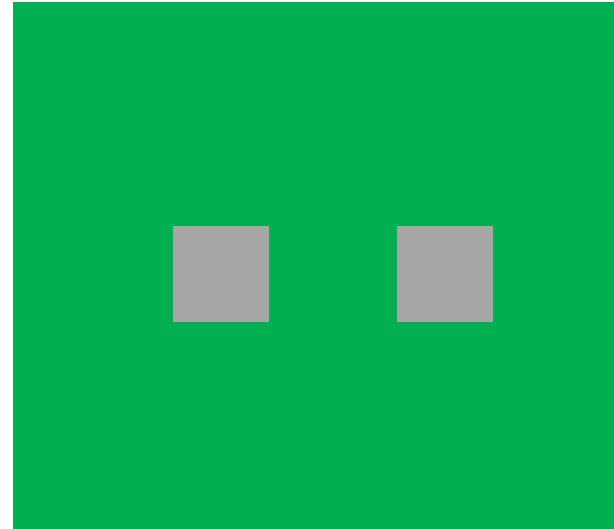


Top View

Alignment, UV Expose and Develop Photo Resist (PR)

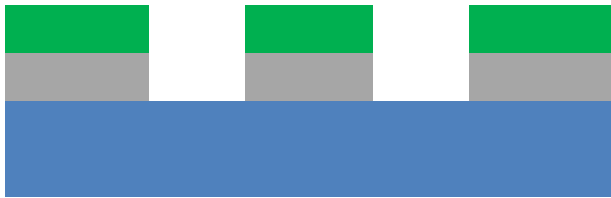


Side View

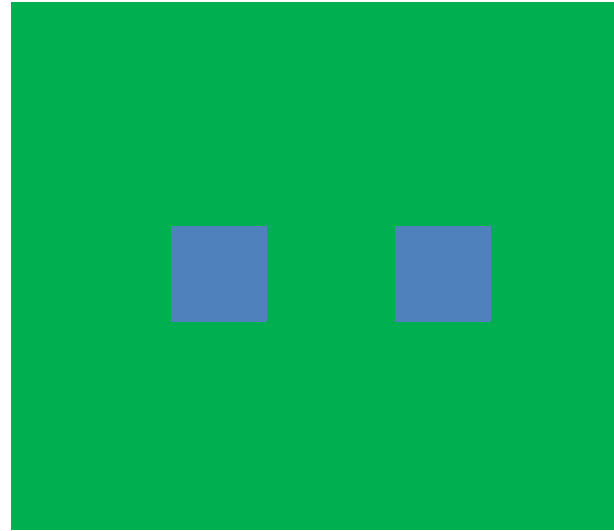


Top View

Oxide Etched



Side View

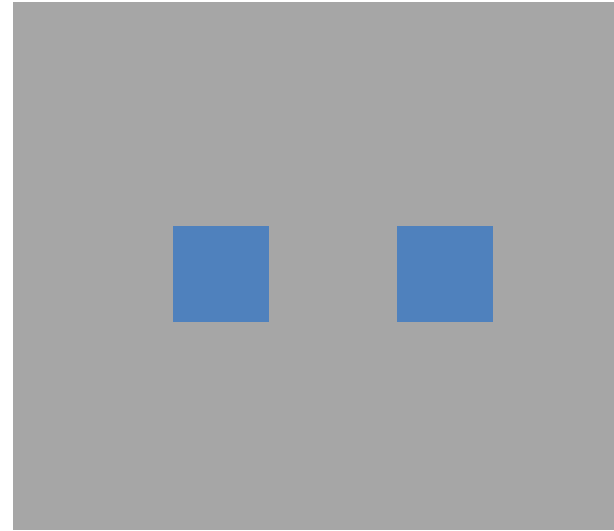


Top View

Remove Photo Resist (PR)



Side View

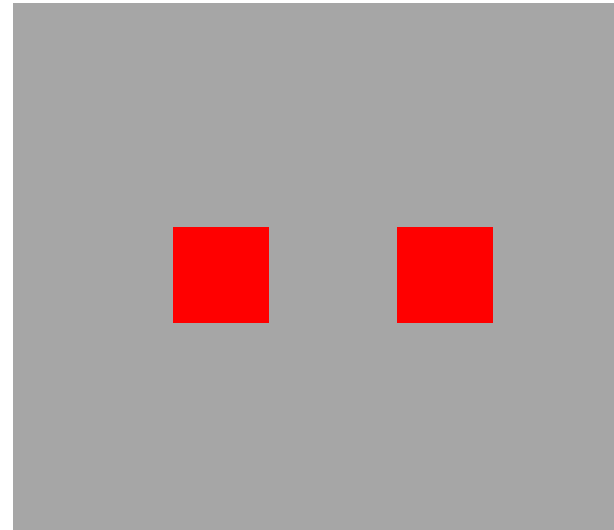


Top View

Doping (implantation or diffusion)

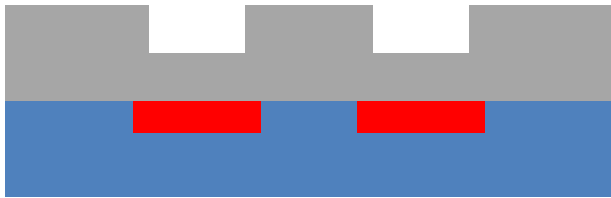


Side View

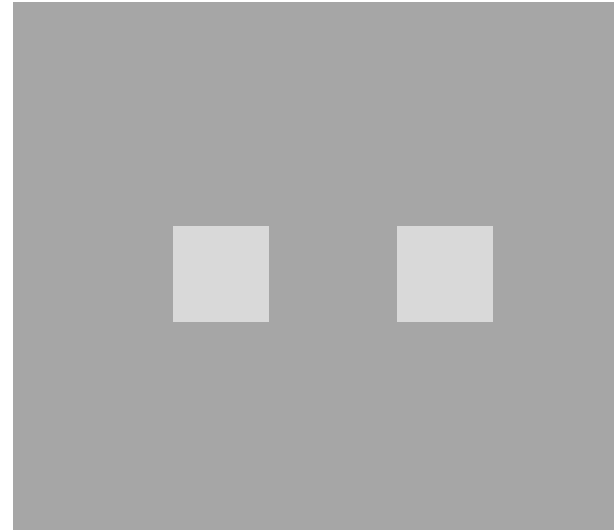


Top View

Grow Field Oxide (wet/dry) and dopant diffusion



Side View

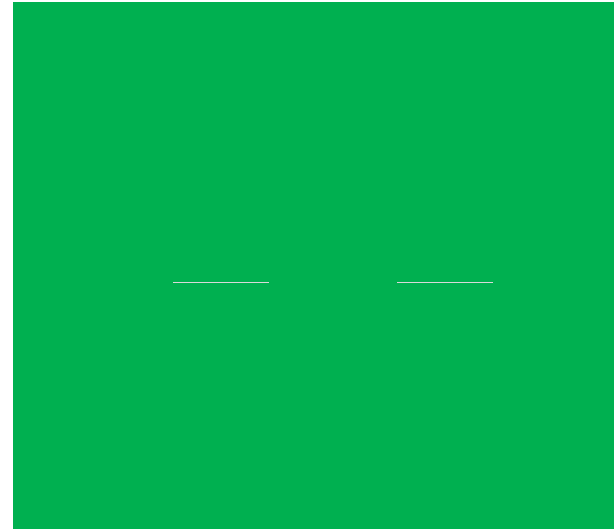


Top View

Spin-on Photo Resist (PR)



Side View

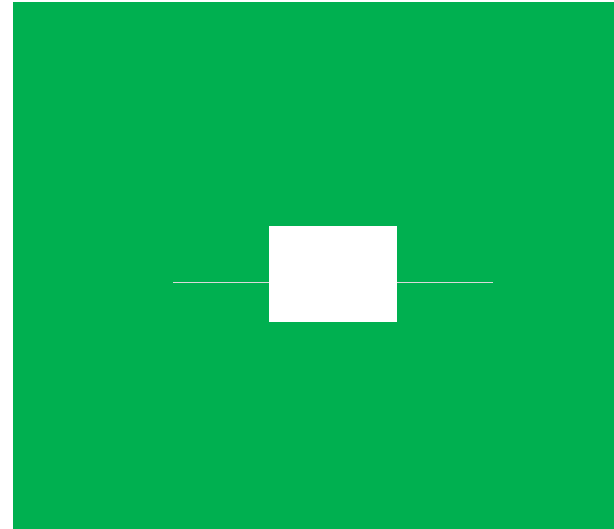


Top View

Alignment, UV Expose and Develop Photo Resist (PR)

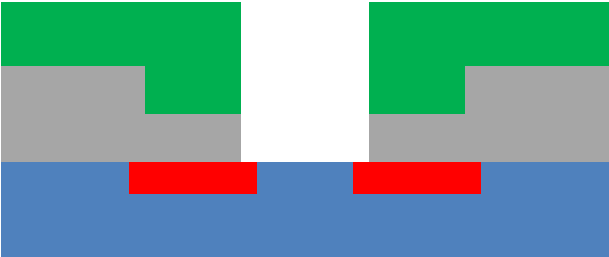


Side View

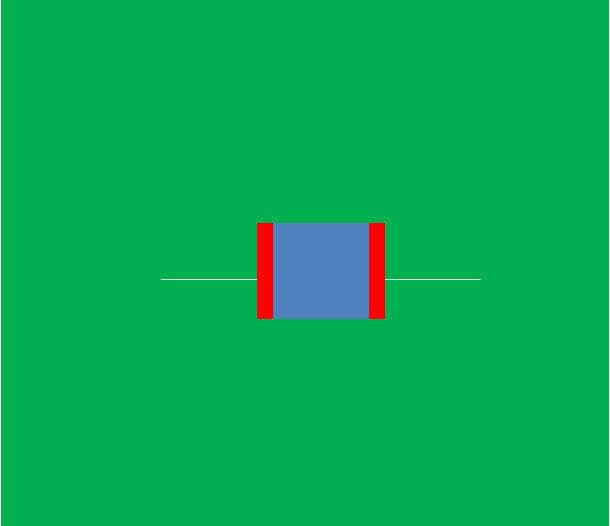


Top View

Oxide Etched

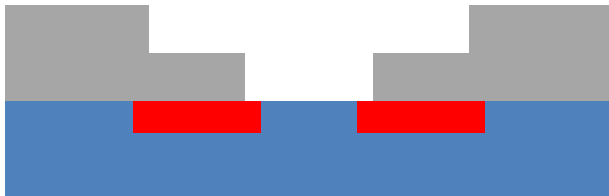


Side View

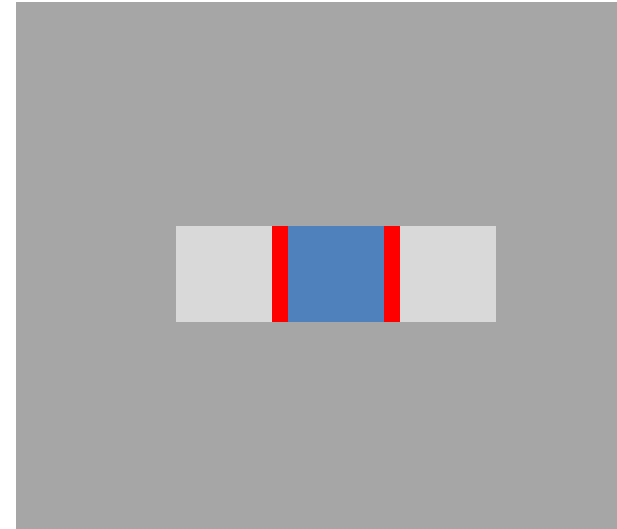


Top View

Remove Photo Resist (PR)

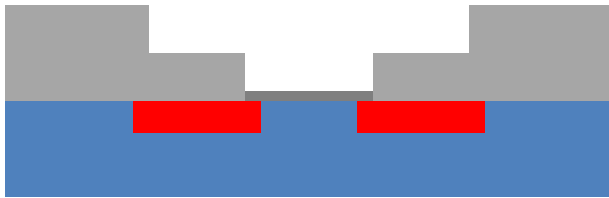


Side View

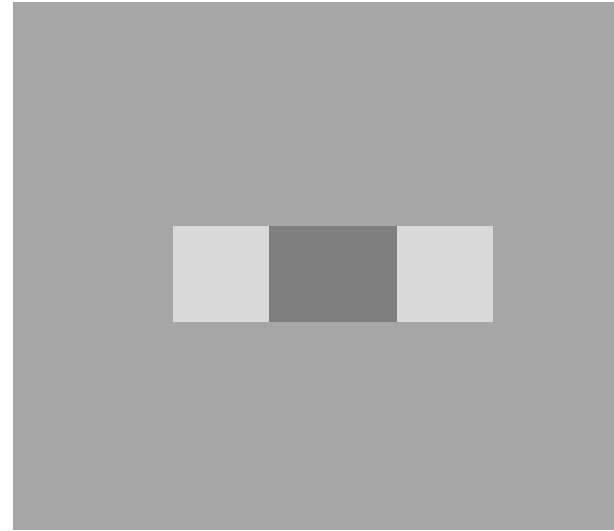


Top View

Grow Gate Oxide (dry)



Side View

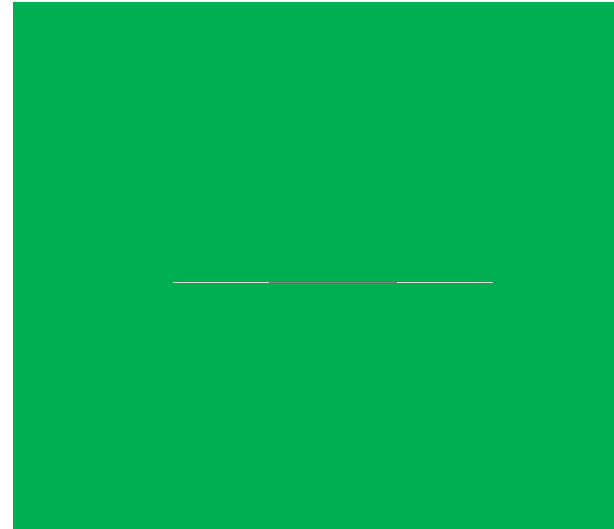


Top View

Spin-on Photo Resist (PR)



Side View

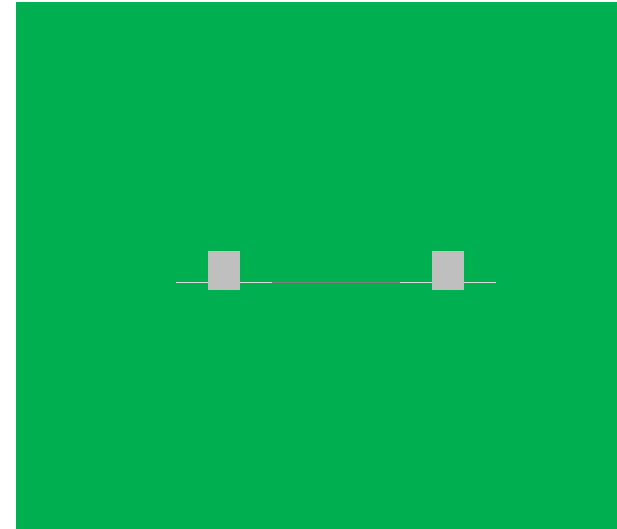


Top View

Alignment, UV Expose and Develop Photo Resist (PR)

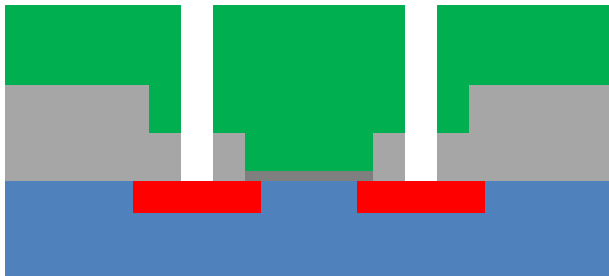


Side View

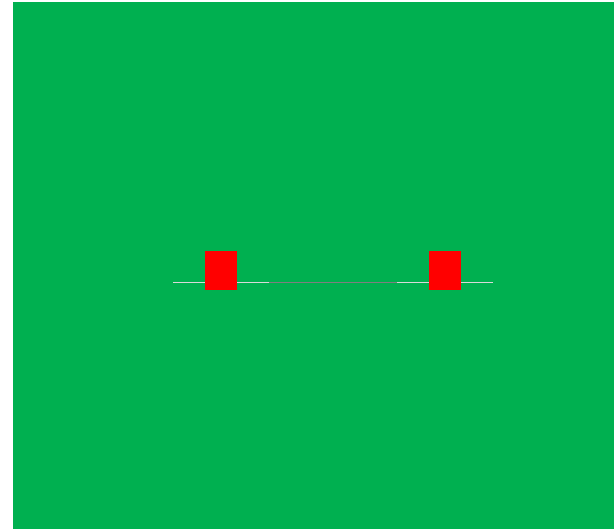


Top View

Field Oxide Etched

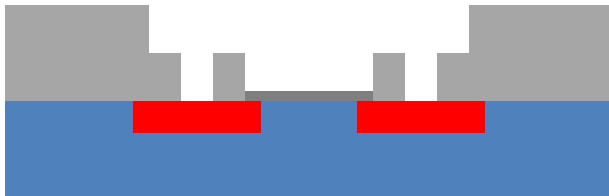


Side View

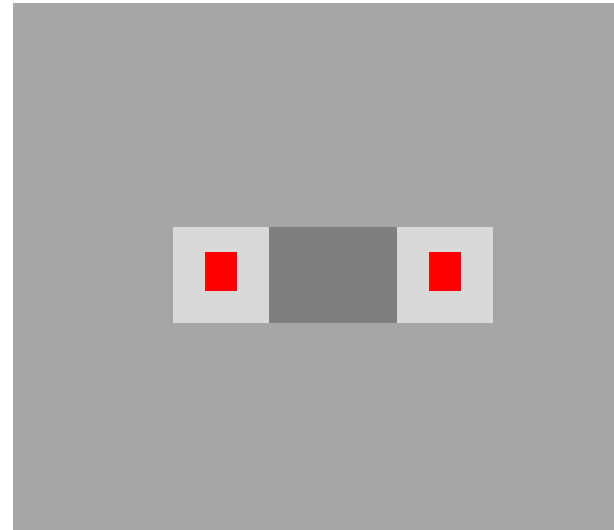


Top View

Field Oxide Etched

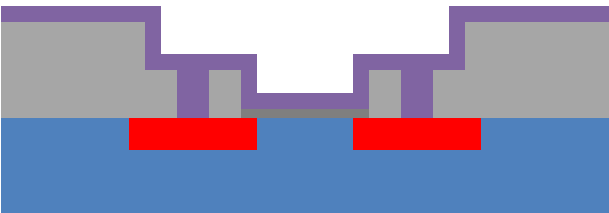


Side View

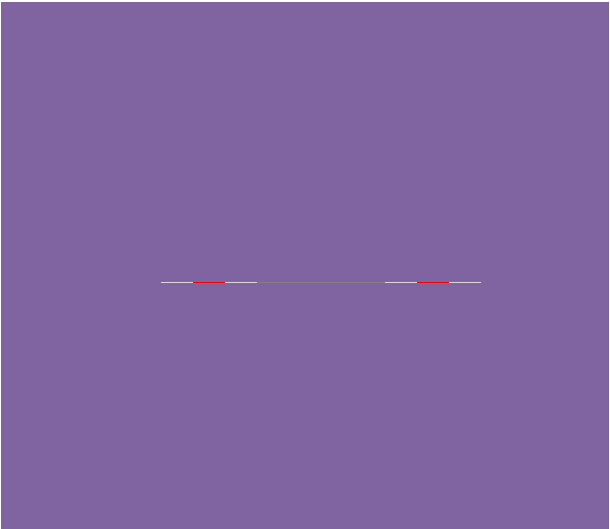


Top View

Metal (e.g., Aluminum) deposition

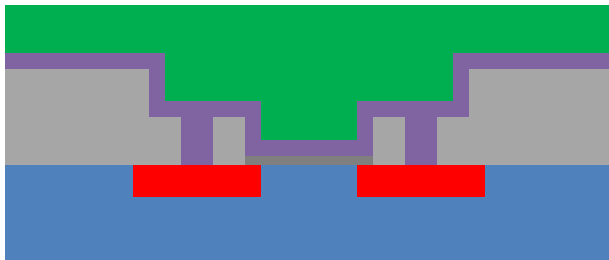


Side View

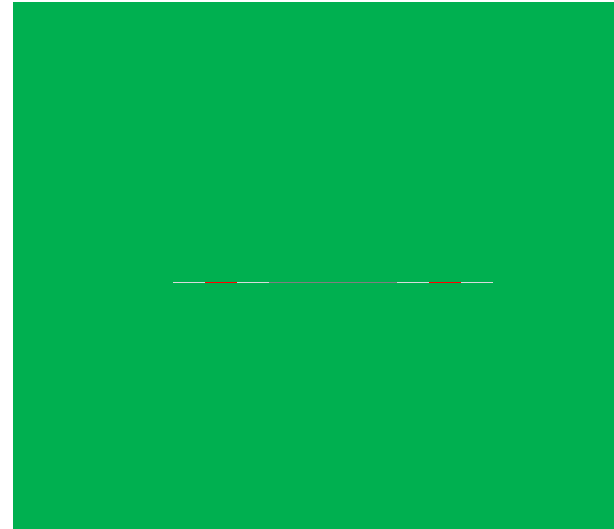


Top View

Spin-on Photo Resist (PR)

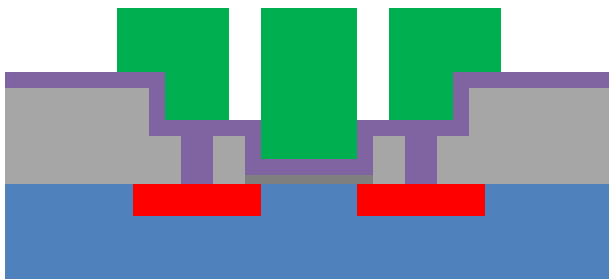


Side View

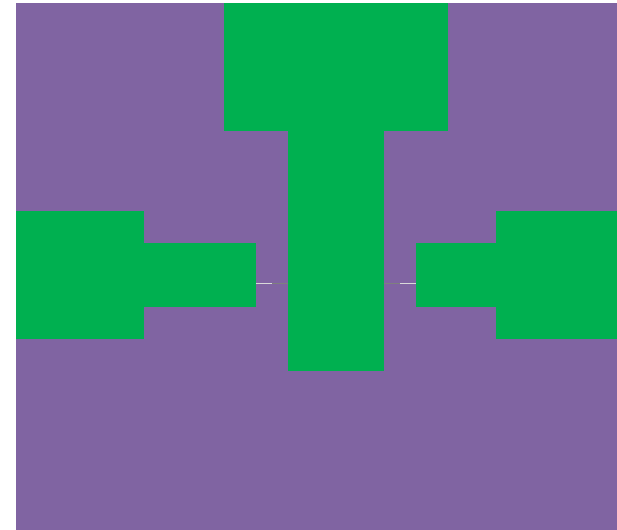


Top View

Alignment, UV Expose and Develop Photo Resist (PR)

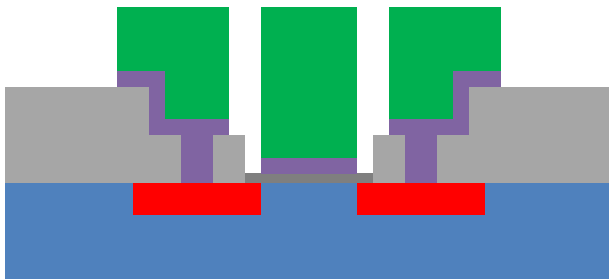


Side View

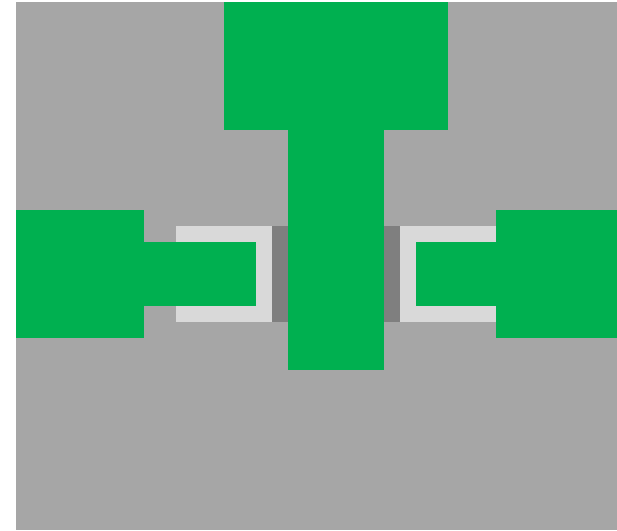


Top View

Aluminum Etched

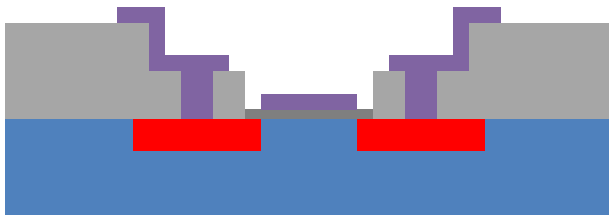


Side View

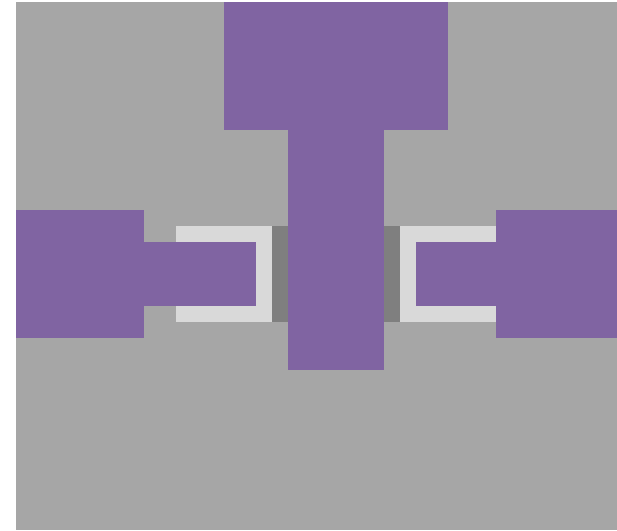


Top View

Remove Photo Resist (PR), annealing - complete



Side View



Top View